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January 2008

74LVT244, 74LVTH244 Low Voltage Octal Buffer/Line Driver with 3-STATE Outputs

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH244), also available without bushold feature (74LVT244)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32mA/+64mA
- Functionally compatible with the 74 series 244
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human-body model > 2000V
 - Machine model > 200V
 - Charged-device model > 1000V

General Description

The LVT244 and LVTH244 are octal buffers and line drivers designed to be employed memory address drivers, clock drivers and bus enter ransmitters or receivers which provide improve C box density.

The LVTH244 data in. is in ide if old, elinimating the need for external properties to hold unused inputs.

These oc 1 but is and the drivers are designed for low-voltice (3...1) Volume reactions, but with the capability to row the interface to a 57 environment. The LVT244 of Lorentz TH24- are fabricated with an advanced BiCMOS technology to achieve high specific peration sin har to 5V AB1 hille maintaining low power dissipation.

Ordering Informa on

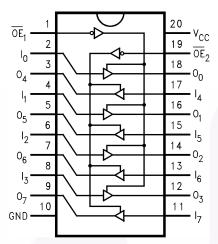
	Pa age	2 K K K CO'
Order Num' er	Mulhi.	Package Description
74LVT244 M	20B	20- Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
7 _VI2 1S2	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
VT24 ISA	MSA2ป	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74L TO +MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm
	OL	Wide
74LVTh?44WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVT!1244SJ	M25D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVTH244MSA	MCA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74LVTH244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

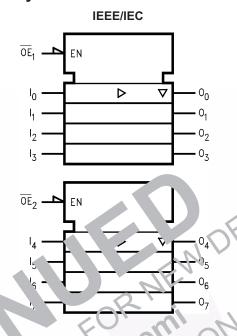
Connection Diagram



Pin Description

Pin Names	Description	
\overline{OE}_1 , \overline{OE}_2	3-STATE Output Enable Inputs	
I ₀ –I ₇	Inputs	
O ₀ –O ₇	Output	

Logic Symbol



Truth Tables

Inputs OE ₁ I _n	Outputs (Pins 12, 14, 16, 18)
L W	L
OL SCH	Н
X H	Z

Inp	uts	Outputs
OE ₂	In	(Pins 3, 5, 7, 9)
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +4.6V
V _I	DC Input Voltage	-0.5V to +7.0V
Vo	DC Output Voltage	
	Output in 3-STATE	-0.5V to +7.0V
	Output in HIGH or LOW State ⁽¹⁾	-0.5V to +7.0V
I _{IK}	DC Input Diode Current, V _I < GND	-50mA
I _{OK}	DC Output Diode Current, V _O < GND	-50mA
Io	DC Output Current, V _O > V _{CC}	
	Output at HIGH State	64mA
	Output at LOW State	128mA
I _{CC}	DC Supply Current per Supply Pin	±64mA
I _{GND}	DC Ground Current per Ground Pin	±128mA
T _{STG}	Storage Temperature	-65° C tc → 150° C

Note:

1. In Absolute Maximum Rating must be of a ved.

Recommended Operation Corditions

The Recommended Oproving Conditions able defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend excretely a more signing to assolute maximum ratings.

Symb	Paranteter	Min	Max	Units
	Single oltage	2.7	3.6	V
VI	nput Voltage	0	5.5	V
ГОН	HIGH Level Output Current		-32	mA
JL J	LOW-Leve! Output Current		64	mA
TA	Free-Air Operating Temperature	-40	85	°C
Δ+/ ΔV	Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$	0	10	ns/V

DC Electrical Characteristics

	Vcc		T A =-	40°C to +	85°C		
Parameter	(V)	Conditions	Min.	Typ. ⁽²⁾	Max.	Units	
Input Clamp Diode Voltage	2.7	I _I = -18mA			-1.2	V	
Input HIGH Voltage	2.7–3.6	$V_0 \le 0.1V$ or	2.0			V	
Input LOW Voltage	2.7–3.6	$V_O \ge V_{CC} - 0.1V$			0.8	V	
Output HIGH Voltage	2.7–3.6	$I_{OH} = -100 \mu A$	V _{CC} -0.2			V	
	2.7	$I_{OH} = -8mA$	2.4				
	3.0	$I_{OH} = -32mA$	2.0				
Output LOW Voltage	2.7	$I_{OL} = 100 \mu A$			0.2	V	
		I _{OL} = 24mA			0.5		
	3.0	I _{OL} = 16mA			0.4	5	
		$I_{OL} = 32mA$			0.5		
		I _{OL} = 64mA			0.55		
Bushold Input Minimum	3.0	V _I = 0.8V	75		1	μA	
Drive		V _I = 2.0V	-75	190			
Bushold Input Over-Drive	3.0	(4)	500			μA	
Current to Change State			-5υύ	9(1)		7	
Input Current	3.5	- 5.5V		5 1	10	μA	
Control Pins	3.0	V _I = V or V _{CC}	0/	10	±1		
Data Pins		$V_I = 0V$	2	5/4	-5		
		V _I = V _{C()}	Z.0		1		
Power Off Leakage Irrent	U	$uV \le V_1 \text{ or } V_0 \le 5.5V$	71		±100	μA	
Power up/ Jwn 3-STA	0-1.5V	$V_0 = 0.5 \text{V to } 3.0 \text{V},$			±100	μA	
	6						
STATE O. ut lakage	3.6	$V_0 = 0.5V$			– 5	μA	
2 CTATE vutnut l 22 vara	(30)	W 10V			-		
	3.6	V _C = 3.0V			5	μA	
	3.6	$V_{CC} \leq V_O \leq 5.5V$			10	μA	
Current	W.						
Power Supply Current	3.6	Outputs HIGH			0.19	mA	
Power Supply Cur ent	3.6	Outputs LOW			5	mA	
Power Supply Current	3.6	Outputs Disabled			0.19	mA	
Power Surply Current	3.6	$V_{CC} \le V_O \le 5.5V$,			0.19	mA	
		Outputs Disabled					
Increase in Power Supply	3.6	One Input at V _{CC} – 0.6V,			0.2	mA	
Current		Other Inputs at V _{CC} or GND					
	Input Clamp Diode Voltage Input HIGH Voltage Input LOW Voltage Output HIGH Voltage Output LOW Voltage Bushold Input Minimum Drive Bushold Input Over-Drive Current to Change State Input Current Control Pins Data Pins Power Off Leakage Irrent Power up/ Jwn 3-STA Output C 'ent STATE Output Leakage Unitent 3-STATE Jutput Leakage Current Power Supply Current	Input Clamp Diode Voltage Input HIGH Voltage Input LOW Voltage Output HIGH Voltage 2.7–3.6 2.7 3.0 Output LOW Voltage 2.7 3.0 Output LOW Voltage 2.7 3.0 Output LOW Voltage 2.7 3.0 Bushold Input Minimum Drive Bushold Input Over-Drive Current to Change State Input Current Control Pins Data Pins Power Up Dwn 3-STA Output C ent STATE Output Leakage Turrent 3.6 3-STATE Output Leakage Current Power Supply Current 3.6 Increase in Power Supply 3.6 Increase in Power Supply 3.6 Increase in Power Supply 3.6	$ \begin{array}{ c c c c } \hline \textbf{Parameter} & \textbf{(V)} & \textbf{Conditions} \\ \hline \textbf{Input Clamp Diode Voltage} & 2.7 & \textbf{I}_{1} = -18 \text{mA} \\ \hline \textbf{Input HIGH Voltage} & 2.7-3.6 & \textbf{V}_{O} \leq 0.1 \text{V or} \\ \hline \textbf{Input LOW Voltage} & 2.7-3.6 & \textbf{I}_{OH} = -100 \mu \text{A} \\ \hline \textbf{2.7} & \textbf{I}_{OH} = -8 \text{mA} \\ \hline \textbf{3.0} & \textbf{I}_{OH} = -32 \text{mA} \\ \hline \textbf{3.0} & \textbf{I}_{OH} = -32 \text{mA} \\ \hline \textbf{3.0} & \textbf{I}_{OL} = 24 \text{mA} \\ \hline \textbf{3.0} & \textbf{I}_{OL} = 16 \text{mA} \\ \hline \textbf{I}_{OL} = 32 \text{mA} \\ \hline \textbf{I}_{OL} = 30 \text{mA} \\ \hline \textbf{I}_{OL} = 32 \text{mA} \\ \hline \textbf{I}_$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Parameter	Parameter (V) Conditions Min. Typ. (2) Max.	

Notes:

- 2. All typical values are at $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$.
- 3. Applies to bushold versions only (74LVTH244).
- 4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- 6. This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics⁽⁷⁾

			Conditions	T _A = 25°C		2	
Symbol	Parameter	V _{CC} (V)	$C_L = 50 pF, R_L = 500 \Omega$	Min.	Тур.	Max.	Units
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	(8)		0.8		V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	(8)		-0.8		V

Notes:

- 7. Characterized in SOIC package. Guaranteed parameter, but not tested.
- 8. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

			T _A = - C _L = 5	-40°C 'o -	\rightarrow	N	Or
		V _{cc}	= 3.31	0. 1	√ _{CC} =	2.7Y	
Symbol	Parameter	Min.	(9)	N.	Min.	Max.	Units
t _{PLH}	Propagation Delay, Data to Output	1		3.8	1.1	4.0	ns
t _{PHL}		3		5.9	1.3	4.2	
t _{PZH}	Output Enable Time	1.		4.5	1.1	5.3	ns
t _{PZL}		1.4		4.4	1.4	5.0	
t _{PHZ}	Output Disable Time	1.9		4.9	1.9	5.1	ns
t _{PLZ}		1.8		4.4	1.8	4.4	
t _{OSHL} , t _{OSLH}	Output to an at S v(10)	0,,		1.0		1.0	ns

Notes:

- 9. All typical values are $\frac{1}{2}$ 3.3V T_A = 25°C.
- 10. Skew de. as absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, or the same direction, or LOW-to-HIGH (t_{CCLH}). Parameter guaranteed by design.

Cap Litange (11)

Symbol	Pararieter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$, $V_I = 0V$ or V_{CC}	3	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC}	6	pF

Note:

11. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

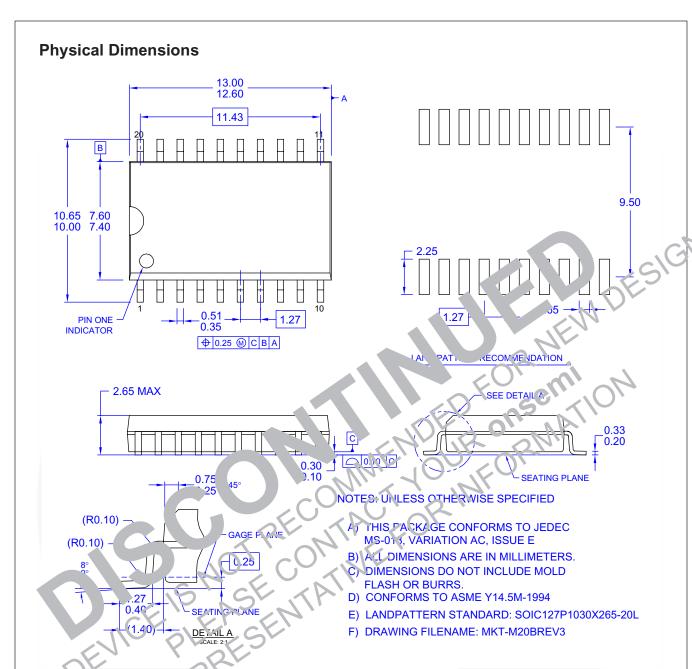


Figure 1. 20-Levi Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued) 12.6±0.10 0.40 TYP -A-20 11 12 11 5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-3.9 (2.13)△ 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT. J.6 TYP 1.27 ALL LEAD TIPS △ 0.1 C 2.1 MAX.--C-0.15 - 0.255.35-0.51 1.27 TYP 7° TYP ARE IN MILLIMATER GAGE PLANE 0°-8° TYP CONFORMS TO LIAU EDG-7320 REGISTRATION ESTABLISHED IN DECEMBER, 1998. D.Y.L.NSIONS ARE EXCLUSIVE OF TULYRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60 ± 0.15 SEATING PLANE 1.25 -DETAIL A

M20DREVC

Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued) 7.2±0.30 0.68 TYP В 9.12 5.58 5.3±0.30 7.8 10 3.9 ○ 0.2 C A B PIN #1 IDENT. RECOMMENDATIONS △ 0.10 C ALL LEAD TIPS 1.75±u 2.0 MAX. 0.65 TYP 0.15M L

NOTES

- NFORMS TO JEDIC REGISTRATION ARIATION AC, LATE 1/94.
- DIMENSIONS ARE IN MILLINIZIERS.

DIN'ELISIONS ARE FACLUSIVE C: DURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS CIMENSIONS AND TOLERAILC'S PER ASME Y14.5M - 1994.

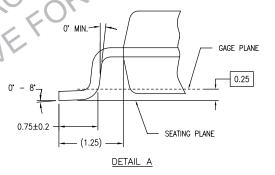


Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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SA20REVB

Physical Dimensions (Continued) 5.5±0.1 -A--0.20 وحا 4.16 6,4 4.4±0.1 -B-3,2 0.2 C B A 0.65 ALL LEAD PIN #1 IDENT. O.1 C 0.90 1.2 -C-0.09-0.20 0.05 0.65

. . .

A. CONFORMS TO JEDEC REDISTRATION MIL-133 VARIATION ACRES NOTE 6, DATE 7/93.

P. D'MENSIONS ARE IN MILLIMETERS.

- C. JIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONS AND TO ERANCES PER ANSI Y14.5M, 1982.

- 8°7 - GAGE PLANE
- 8°7 - GAGE PLANE
- 0.6±0.1- SEATING PLANE
- R0.09min

DETAIL A

MTC20REVD1

Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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